

Appl. No. 10/757,778

Amdt. dated 24 January 2006

Reply to Restriction Requirement of 4 January 2006

Amendments to the Claims:

Please amend the claims as indicated.

1. (Currently Amended) A method to improve a flow rate of imprinting material, said method comprising:
collecting thermal radiation at a target, defining collected thermal energy;
and
transferring said collected thermal energy to said imprinting material by conduction.
2. (Original) The method as recited in claim 1 wherein transferring further includes providing a sufficient quantity of said collected thermal energy to said imprinting material to reduce a viscosity thereof.
3. (Original) The method as recited in claim 1 wherein said imprinting material has a glass transition temperature associated therewith and transferring further includes providing a sufficient quantity of said collected thermal energy to said imprinting material to provide said imprinting material with a temperature greater than said glass transition temperature.
4. (Original) The method as recited in claim 1 wherein transferring further includes providing a sufficient quantity of said collected thermal energy to said imprinting material to cross-link said imprinting material.
5. (Original) The method as recited in claim 1 wherein collecting said thermal radiation further includes propagating said thermal radiation through said imprinting material.

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6. (Currently Amended) The method as recited in claim 1 further including ~~disposing~~ positioning said imprinting material upon a substrate, wherein collecting said thermal radiation further includes propagating said thermal radiation through said substrate.

7. (Currently Amended) The method as recited in claim 1 further including providing a body having first and second opposed sides, with collecting further including collecting said thermal radiation proximate to said first side and transferring said ~~collection~~ thermal radiation to said second side.

8. (Currently Amended) The method as recited in claim 7 wherein providing further includes disposing said imprinting layer on said second side.

9. (Currently Amended) The method as recited in claim 1 further including providing a substrate having first and second opposed sides, with collecting further including collecting said thermal radiation proximate to said first side and transferring said ~~collection~~ thermal radiation to said second side.

10. (Currently Amended) The method as recited in claim 1 wherein said method further includes positioning a mold, having a plurality of protrusions and recesses, proximate to said imprinting material, with said imprinting material substantially filling said plurality of recesses, and impinging ~~ultraviolet radiation~~ actinic energy upon said imprinting material to polymerize said imprinting material.

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11. (Currently Amended) A method to improve a flow rate of imprinting material, said method comprising:
impinging thermal radiation upon a target to collect thermal energy therein,
defining collected thermal energy with said imprinting material in superimposition
with said target, ~~defining collected thermal energy~~; and
conducting said collected thermal energy to said imprinting material to
increase a temperature thereof.
12. (Currently Amended) The method as recited in claim 11
wherein said method further includes positioning a mold, having a plurality of
protrusions and recesses, proximate to said imprinting material, with said
imprinting material substantially filling said plurality of recesses, and impinging
~~ultraviolet radiation~~ actinic energy upon said imprinting material to polymerize
said imprinting material.
13. (Currently Amended) The method as recited in claim 11
wherein conducting said collected thermal energy further includes reducing a
viscosity of said imprinting material.
14. (Currently Amended) The method as recited in claim 11
wherein said imprinting material has a glass transition temperature associated
therewith and conducting further includes providing a sufficient quantity of said
collected ~~radiation~~ thermal energy to said imprinting material to provide said
imprinting material with a temperature greater than said glass transition
temperature.
15. (Currently Amended) The method as recited in claim 11
wherein conducting further includes providing a sufficient quantity of said
collected ~~radiation~~ thermal energy to said imprinting material to cross-link said
imprinting material.

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16. (Currently Amended) The method as recited in claim 11 wherein said method further includes disposing positioning said imprinting material upon a surface of said target.

17. (Currently Amended) The method as recited in claim 11 wherein impinging said thermal radiation further includes propagating said radiation through said imprinting material.

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